

# Dual D Flip-Flop with Set and Reset

## MC74HC74A, MC74HCT74A

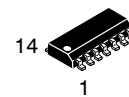
The MC74HC74A is identical in pinout to the LS74. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This device consists of two D flip-flops with individual Set, Reset, and Clock inputs. Information at a D-input is transferred to the corresponding Q output on the next positive going edge of the clock input. Both Q and  $\bar{Q}$  outputs are available from each flip-flop. The Set and Reset inputs are asynchronous.

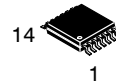
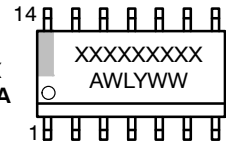
### Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range:  
2.0 to 6.0 V (HC), 4.5 to 5.5 V (HCT)
- Low Input Current: 1.0  $\mu$ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the JEDEC Standard No. 7.0 A Requirements
- Chip Complexity: 136 FETs or 34 Equivalent Gates
- -Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

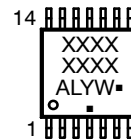
### MARKING DIAGRAMS



SOIC-14  
D SUFFIX  
CASE 751A



TSSOP-14  
DT SUFFIX  
CASE 948G



XXXX = Specific Device Code  
A = Assembly Location  
WL, L = Wafer Lot  
Y = Year  
WW, W = Work Week  
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 9 of this data sheet.

## MC74HC74A, MC74HCT74A

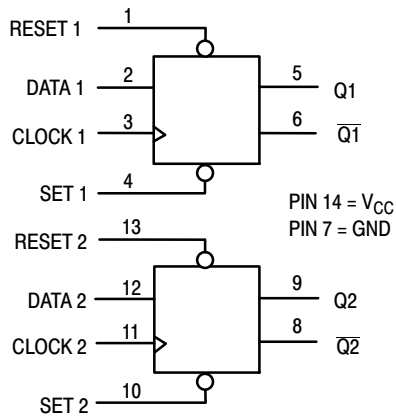


Figure 1. Logic Diagram

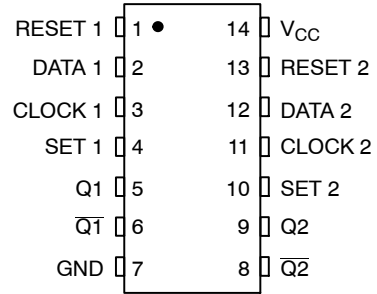


Figure 2. Pinout (Top View)

### FUNCTION TABLE

Inputs				Outputs	
Set	Reset	Clock	Data	Q	$\overline{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H*	H*
H	H	$\nearrow$	H	H	L
H	H	$\searrow$	L	L	H
H	H	L	X	No Change	No Change
H	H	H	X	No Change	No Change
H	H	$\curvearrowright$	X	No Change	No Change

\*Both outputs will remain high as long as Set and Reset are low, but the output states are unpredictable if Set and Reset go high simultaneously.

# MC74HC74A, MC74HCT74A

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	−0.5 to +6.5	V
V <sub>IN</sub>	DC Input Voltage	−0.5 to V <sub>CC</sub> + 0.5	V
V <sub>OUT</sub>	DC Output Voltage	−0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IN</sub>	DC Input Diode Current, per Pin	±20	mA
I <sub>OUT</sub>	DC Output Diode Current, per Pin	±25	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	±50	mA
I <sub>IK</sub>	Input Clamp Current (V <sub>IN</sub> < 0 or V <sub>IN</sub> > V <sub>CC</sub> )	±20	mA
I <sub>OK</sub>	Output Clamp Current (V <sub>OUT</sub> < 0 or V <sub>OUT</sub> > V <sub>CC</sub> )	±20	mA
T <sub>STG</sub>	Storage Temperature Range	−65 to +150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T <sub>J</sub>	Junction Temperature Under Bias	±150	°C
θ <sub>JA</sub>	Thermal Resistance (Note 1)	SOIC−14 TSSOP−14 116 150	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 25°C	SOIC−14 TSSOP−14 1077 833	mW
MSL	Moisture Sensitivity	Level 1	–
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34 UL 94 V−0 @ 0.125 in	–
V <sub>ESD</sub>	ESD Withstand Voltage (Note 2)	Human Body Model Charged Device Model > 2000 N/A	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 76mm-by-114mm, 2-ounce copper trace no air flow per JESD51-7.
2. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
<b>MC74HC</b>				
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input Voltage, Output Voltage (Referenced to GND) (Note 3)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Free-Air Temperature	−55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	V <sub>CC</sub> = 2.0 V V <sub>CC</sub> = 4.5 V V <sub>CC</sub> = 6.0 V 0 0 0	1000 500 400	ns
<b>MC74HCT</b>				
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	4.5	5.5	V
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input Voltage, Output Voltage (Referenced to GND) (Note 3)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Free-Air Temperature	−55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	0	500	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

3. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open.

# MC74HC74A, MC74HCT74A

## DC ELECTRICAL CHARACTERISTICS (MC74HC74A)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limit			Unit
				–55 to 25°C	≤ 85°C	≤ 125°C	
V <sub>IH</sub>	Minimum High-Level Input Voltage	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V  I <sub>OUT</sub>   ≤ 20 µA	2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	V
V <sub>IL</sub>	Maximum Low-Level Input Voltage	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V  I <sub>OUT</sub>   ≤ 20 µA	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	0.5 0.9 1.35 1.8	V
V <sub>OH</sub>	Minimum High-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>					V
		I <sub>OUT</sub>   ≤ 20 µA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	
		I <sub>OUT</sub>   ≤ 2.4 mA	3.0	2.48	2.34	2.2	
		I <sub>OUT</sub>   ≤ 4.0 mA	4.5	3.98	3.84	3.7	
V <sub>OL</sub>	Maximum Low-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>					V
		I <sub>OUT</sub>   ≤ 20 µA	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	
		I <sub>OUT</sub>   ≤ 2.4 mA	3.0	0.26	0.33	0.4	
		I <sub>OUT</sub>   ≤ 4.0 mA	4.5	0.26	0.33	0.4	
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0	±0.1	±1.0	±1.0	µA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>IN</sub> = V <sub>CC</sub> or GND I <sub>OUT</sub> = 0 µA	6.0	2.0	20	80	µA

## AC ELECTRICAL CHARACTERISTICS (MC74HC74A)

Symbol	Parameter	V <sub>CC</sub> V	Guaranteed Limit			Unit
			– 55 to 25°C	≤ 85°C	≤ 125°C	
f <sub>max</sub>	Maximum Clock Frequency (50% Duty Cycle) (Figure 4)	2.0 3.0 4.5 6.0	6.0 15 30 35	4.8 10 24 28	4.0 8.0 20 24	MHz
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Clock to Q or $\bar{Q}$ (Figure 4)	2.0 3.0 4.5 6.0	100 75 20 17	125 90 25 21	150 120 30 26	ns
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Set or Reset to Q or $\bar{Q}$ (Figure 5)	2.0 3.0 4.5 6.0	105 80 21 18	130 95 26 22	160 130 32 27	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figure 4)	2.0 3.0 4.5 6.0	75 30 15 13	95 40 19 16	110 55 22 19	ns
C <sub>in</sub>	Maximum Input Capacitance	—	10	10	10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Per Enabled Output)	5.0	Typical @ 25°C, V <sub>CC</sub> = 5.0 V			pF
			32			

4. Used to determine the no-load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ .

# MC74HC74A, MC74HCT74A

## TIMING REQUIREMENTS (MC74HC74A)

Symbol	Parameter	V <sub>CC</sub> V	Guaranteed Limit			Unit
			-55 to 25°C	≤ 85°C	≤ 125°C	
t <sub>su</sub>	Minimum Setup Time, Data to Clock (Figure 6)	2.0	80	100	120	ns
		3.0	35	45	55	
		4.5	16	20	24	
		6.0	14	17	20	
t <sub>h</sub>	Minimum Hold Time, Clock to Data (Figure 6)	2.0	3.0	3.0	3.0	ns
		3.0	3.0	3.0	3.0	
		4.5	3.0	3.0	3.0	
		6.0	3.0	3.0	3.0	
t <sub>rec</sub>	Minimum Recovery Time, Set or Reset Inactive to Clock (Figure 5)	2.0	8.0	8.0	8.0	ns
		3.0	8.0	8.0	8.0	
		4.5	8.0	8.0	8.0	
		6.0	8.0	8.0	8.0	
t <sub>w</sub>	Minimum Pulse Width, Clock (Figure 4)	2.0	60	75	90	ns
		3.0	25	30	40	
		4.5	12	15	18	
		6.0	10	13	15	
t <sub>w</sub>	Minimum Pulse Width, Set or Reset (Figure 5)	2.0	60	75	90	ns
		3.0	25	30	40	
		4.5	12	15	18	
		6.0	10	13	15	
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Times (Figure 4)	2.0	1000	1000	1000	ns
		3.0	800	800	800	
		4.5	500	500	500	
		6.0	400	400	400	

# MC74HC74A, MC74HCT74A

## DC ELECTRICAL CHARACTERISTICS (MC74HCT74A)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limit			Unit
				−55 to 25°C	≤ 85°C	≤ 125°C	
V <sub>IH</sub>	Minimum High-Level Input Voltage	V <sub>out</sub> = 0.1 V or V <sub>CC</sub> − 0.1 V  I <sub>out</sub>   ≤ 20 μA	4.5 5.5	2.0 2.0	2.0 2.0	2.0 2.0	V
V <sub>IL</sub>	Maximum Low-Level Input Voltage	V <sub>out</sub> = 0.1 V or V <sub>CC</sub> − 0.1 V  I <sub>out</sub>   ≤ 20 μA	4.5 5.5	0.8 0.8	0.8 0.8	0.8 0.8	V
V <sub>OH</sub>	Minimum High-Level Output Voltage	V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub>  I <sub>out</sub>   ≤ 20 μA	4.5 5.5	4.4 5.4	4.4 5.4	4.4 5.4	V
		V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub>  I <sub>out</sub>   ≤ 4.0 mA	4.5	3.98	3.84	3.7	
V <sub>OL</sub>	Maximum Low-Level Output Voltage	V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub>  I <sub>out</sub>   ≤ 20 μA	4.5 5.5	0.1 0.1	0.1 0.1	0.1 0.1	V
		V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub>  I <sub>out</sub>   ≤ 4.0 mA	4.5	0.26	0.33	0.4	
I <sub>in</sub>	Maximum Input Leakage Current	V <sub>in</sub> = V <sub>CC</sub> or GND	5.5	± 0.1	± 1.0	± 1.0	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>in</sub> = V <sub>CC</sub> or GND I <sub>out</sub> = 0 μA	5.5	2.0	20	80	μA
ΔI <sub>CC</sub>	Additional Quiescent Supply Current	V <sub>in</sub> = 2.4 V, Any One Input V <sub>in</sub> = V <sub>CC</sub> or GND, Other Inputs I <sub>out</sub> = 0 μA	5.5	≥ −55°C	25°C to 125°C		mA
				2.9	2.4		

## AC ELECTRICAL CHARACTERISTICS (MC74HCT74A)

Symbol	Parameter	Guaranteed Limit			Unit
		-55 to 25°C	≤ 85°C	≤ 125°C	
f <sub>max</sub>	Maximum Clock Frequency (50% Duty Cycle) (Figure 4)	30	24	20	MHz
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Clock to Q or $\bar{Q}$ (Figure 4)	24	30	36	ns
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Set or Reset to Q or $\bar{Q}$ (Figure 5)	24	30	36	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figure 4)	15	19	22	ns
C <sub>in</sub>	Maximum Input Capacitance	10	10	10	pF

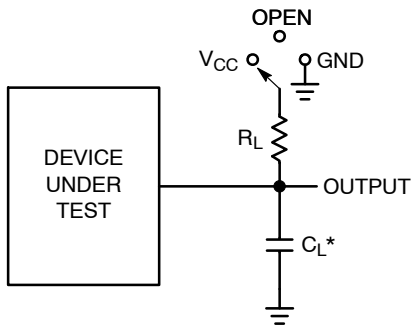
C <sub>PD</sub>	Power Dissipation Capacitance (Per Enabled Output)*	Typical @ 25°C, V <sub>CC</sub> = 5.0 V	pF
		32	

5. Used to determine the no-load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ .

## TIMING REQUIREMENTS (MC74HCT74A)

Symbol	Parameter	Fig.	Guaranteed Limit						Units
			−55 to 25°C		≤ 85°C		≤ 125°C		
			Min	Max	Min	Max	Min	Max	
t <sub>su</sub>	Minimum Setup Time, Data to Clock	6	15		19		22		ns
t <sub>h</sub>	Minimum Hold Time, Clock to Data	6	3		3		3		ns
t <sub>rec</sub>	Minimum Recovery Time, Set or Reset Inactive to Clock	5	6		8		9		ns
t <sub>w</sub>	Minimum Pulse Width, Clock	4	15		19		22		ns
t <sub>w</sub>	Minimum Pulse Width, Set or Reset	5	15		19		22		ns
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Times	4		500		500		500	ns

# MC74HC74A, MC74HCT74A



\*C<sub>L</sub> Includes probe and jig capacitance

Test	Switch Position	C <sub>L</sub>	R <sub>L</sub>
t <sub>PLH</sub> / t <sub>PHL</sub>	Open	50 pF	1 kΩ
t <sub>PLZ</sub> / t <sub>PZL</sub>	V <sub>CC</sub>		
t <sub>PHZ</sub> / t <sub>PZH</sub>	GND		

Figure 3. Test Circuit

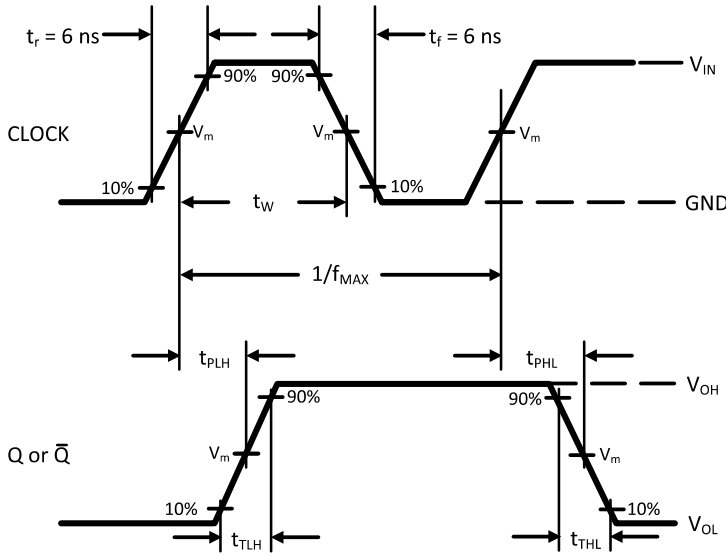


Figure 4.

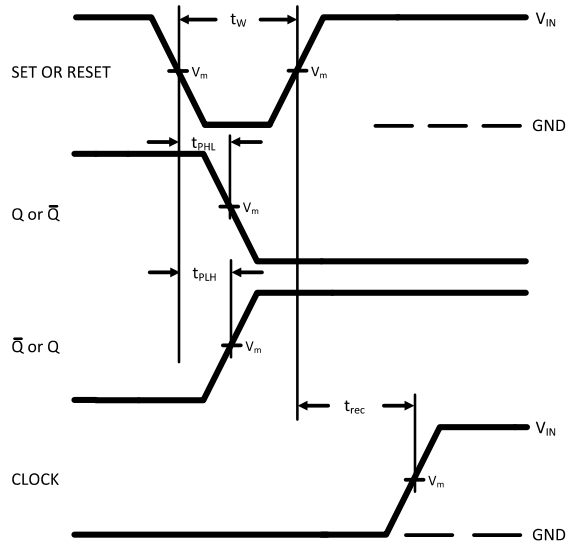


Figure 5.

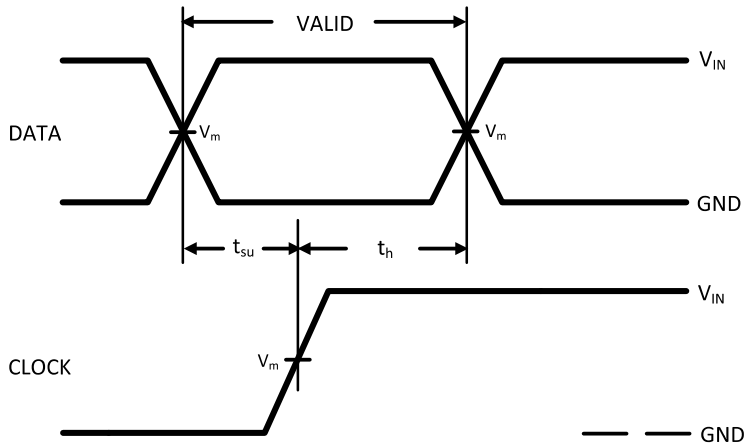


Figure 6.

Device	V <sub>IN</sub> , V	V <sub>m</sub> , V
MC74HC74A	V <sub>CC</sub>	50% x V <sub>CC</sub>
MC74HCT74A	3 V	1.3 V

# MC74HC74A, MC74HCT74A

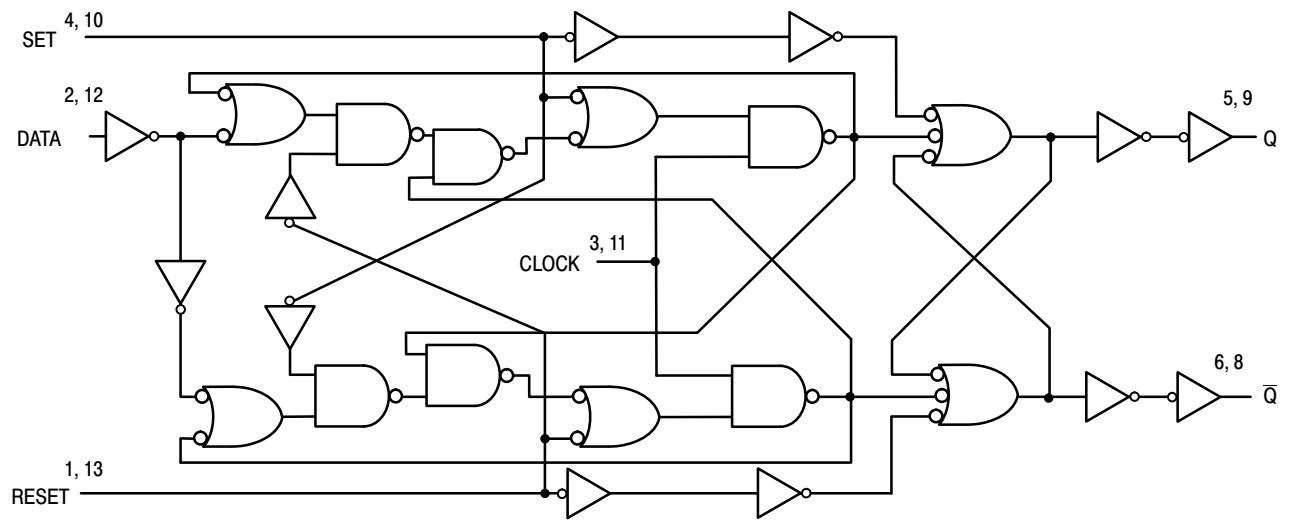


Figure 7. Expanded Logic Diagram



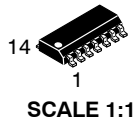
## MC74HC74A, MC74HCT74A

### ORDERING INFORMATION

Device	Marking	Package	Shipping <sup>†</sup>
MC74HC74ADG	HC74AG	SOIC-14	55 Units / Rail
MC74HC74ADR2G	HC74AG	SOIC-14	2500 / Tape & Reel
MC74HC74ADTR2G	HC 74A	TSSOP-14	2500 / Tape & Reel
MC74HC74ADTR2G-Q*	HC 74A	TSSOP-14	2500 / Tape & Reel
MC74HCT74ADG*	HCT74AG	SOIC-14	55 Units / Rail
MC74HCT74ADR2G*	HCT74AG	SOIC-14	2500 / Tape & Reel

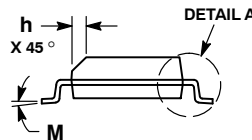
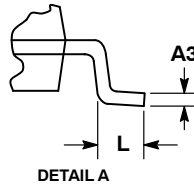
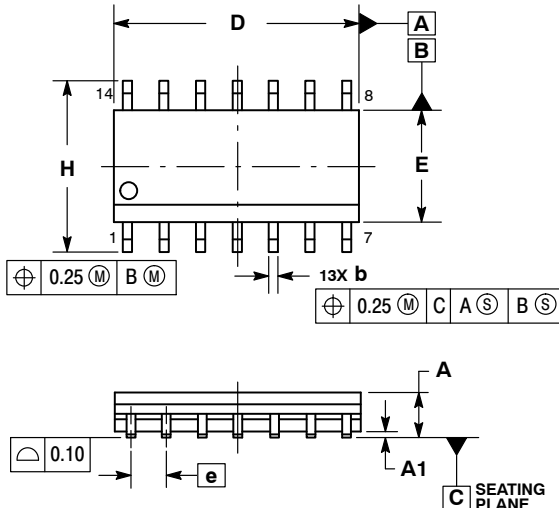
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.



SOIC-14 NB  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016

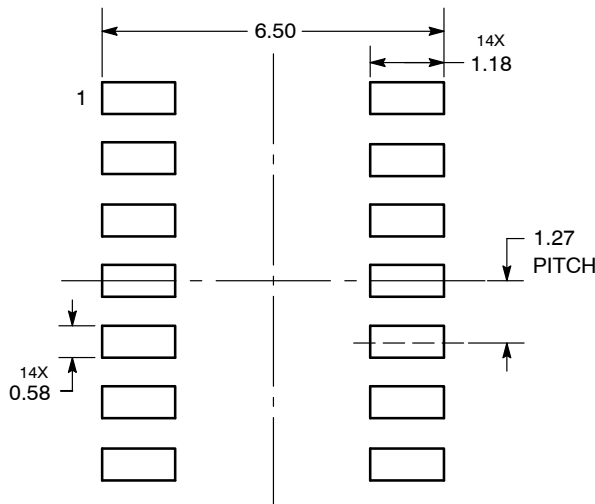


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

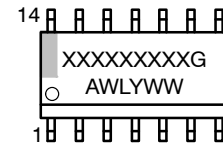
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC  
MARKING DIAGRAM\*



XXXXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42565B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOIC-14 NB	PAGE 1 OF 2

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SOIC-14  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016

STYLE 1:  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. NO CONNECTION  
5. ANODE/CATHODE  
6. NO CONNECTION  
7. ANODE/CATHODE  
8. ANODE/CATHODE  
9. ANODE/CATHODE  
10. NO CONNECTION  
11. ANODE/CATHODE  
12. ANODE/CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

STYLE 2:  
CANCELLED

STYLE 3:  
PIN 1. NO CONNECTION  
2. ANODE  
3. ANODE  
4. NO CONNECTION  
5. ANODE  
6. NO CONNECTION  
7. ANODE  
8. ANODE  
9. ANODE  
10. NO CONNECTION  
11. ANODE  
12. ANODE  
13. NO CONNECTION  
14. COMMON CATHODE

STYLE 4:  
PIN 1. NO CONNECTION  
2. CATHODE  
3. CATHODE  
4. NO CONNECTION  
5. CATHODE  
6. NO CONNECTION  
7. CATHODE  
8. CATHODE  
9. CATHODE  
10. NO CONNECTION  
11. CATHODE  
12. CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

STYLE 5:  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. ANODE/CATHODE  
5. ANODE/CATHODE  
6. NO CONNECTION  
7. COMMON ANODE  
8. COMMON CATHODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. ANODE/CATHODE  
12. ANODE/CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

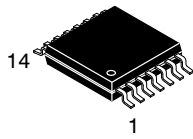
STYLE 6:  
PIN 1. CATHODE  
2. CATHODE  
3. CATHODE  
4. CATHODE  
5. CATHODE  
6. CATHODE  
7. CATHODE  
8. ANODE  
9. ANODE  
10. ANODE  
11. ANODE  
12. ANODE  
13. ANODE  
14. ANODE

STYLE 7:  
PIN 1. ANODE/CATHODE  
2. COMMON ANODE  
3. COMMON CATHODE  
4. ANODE/CATHODE  
5. ANODE/CATHODE  
6. ANODE/CATHODE  
7. ANODE/CATHODE  
8. ANODE/CATHODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. COMMON CATHODE  
12. COMMON ANODE  
13. ANODE/CATHODE  
14. ANODE/CATHODE

STYLE 8:  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. NO CONNECTION  
5. ANODE/CATHODE  
6. ANODE/CATHODE  
7. COMMON ANODE  
8. COMMON ANODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. NO CONNECTION  
12. ANODE/CATHODE  
13. ANODE/CATHODE  
14. COMMON CATHODE

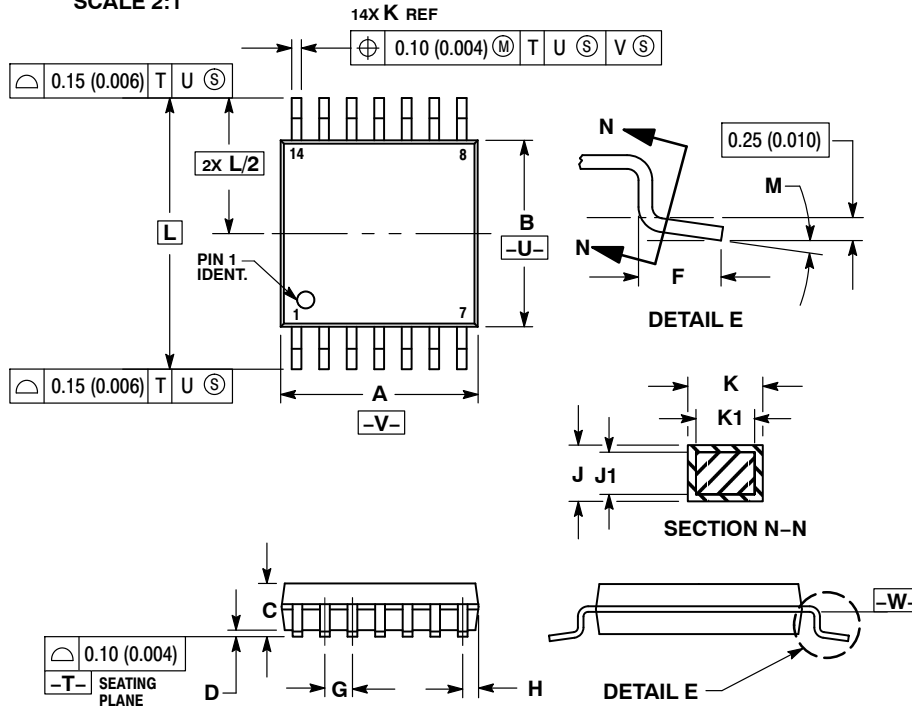
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DESCRIPTION:	SOIC-14 NB	PAGE 2 OF 2

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**TSSOP-14 WB**  
CASE 948G  
ISSUE C

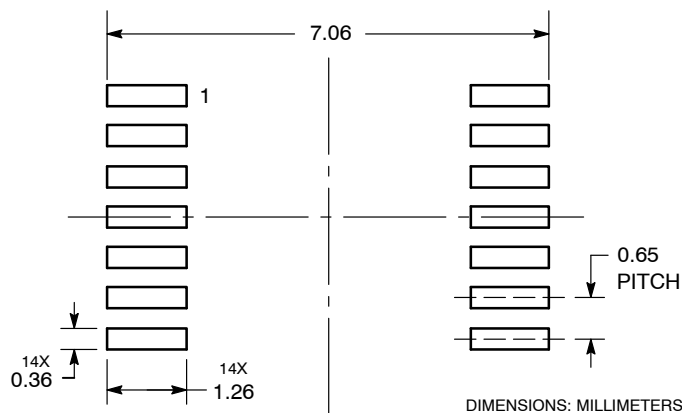
DATE 17 FEB 2016

SCALE 2:1

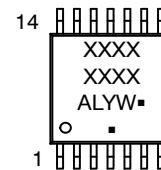

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

**RECOMMENDED  
SOLDERING FOOTPRINT\***


\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC  
MARKING DIAGRAM\***


A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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**DESCRIPTION:** TSSOP-14 WB

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